

SPECIFICATION

产品规格书



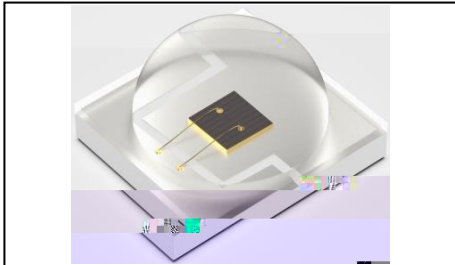
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1. Description 产品介绍

1.1 General Description 产品描述



The IR source color devices are made with AlGaAs on Substrate Light Emitting Diode

红外 LED 由 AlGaAs 三种元素芯片激发而成

The LED package dimension: 3.45mmX3.45mmX2.20mm.

产品尺寸: 3.45mmX3.45mmX2.20mm。

1.2 Features 产品特征

Ceramics Package. 陶瓷封装

Extremely wide viewing angle. 发光角度大

Suitable for all SMT assembly and solder process. 适用于所有的SMT组装和焊接工艺

Available on tape and reel. 适用于载带及卷轴

Moisture sensitive level: Level 1. 防潮等级: Level 1

RoHS compliant. 满足RoHS要求

1.3 Application 产品应用

Article color lamp, lamp belt. 彩色灯条、灯带

Plant lighting, Landscape lighting

植物照明、景观照明、舞台摄影

Hotels, markets, offices, household and other indoor uses. 酒店、商场、办公室、家用及其它室内用途

1.4 Package Dimension 封装尺寸

Fig.1-1 Top view 正面视图

Fig.1-2 Side view 侧面视图

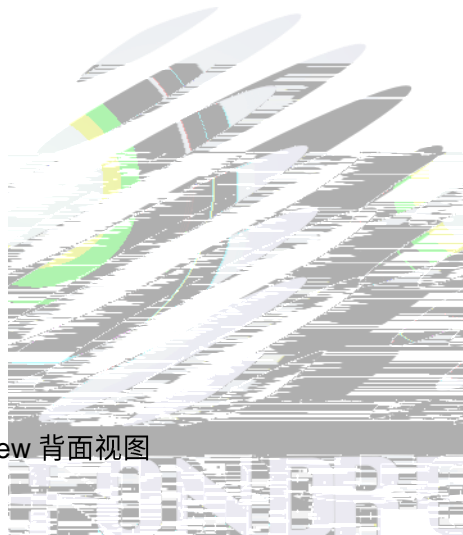


Fig.1-3 Bottom view 背面视图

Fig.1-4 Polarity 极性

Fig.1-5 Soldering patterns 推荐焊盘

Notes 备注:

1. All dimensions units are millimeters. 所有尺寸标注单位为毫米

1.5 Product Parameters 产品参数

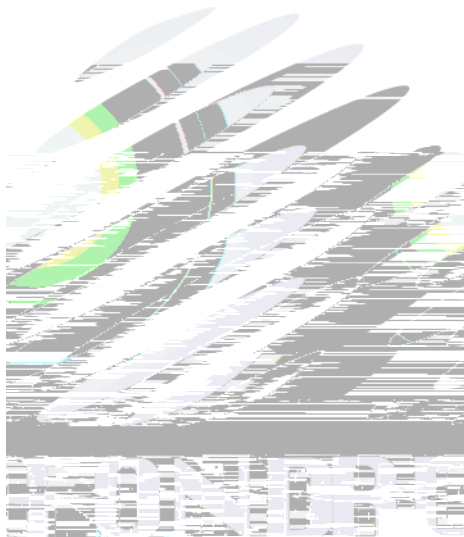
Table 1-1 Electrical / Optical Characteristics at Ts=25°C 电性与光学特性

Item 项目	Symbol 符号	Test Condition 测试条件	Value			Unit 单位
			Min. (最小值)	Typ (典型值)	Max. (最大值)	
Forward Voltage (正向电压)	V _F	I _F =350mA	1.4	---	2.0	V
		I _F =700mA	1.5	---	2.2	V
Total radiant flux (辐射功率)	e	I _F =350mA	250	---	500	mW
		I _F =700mA	450	---	900	mW
Peak Wavelength (峰值波长)	λ	I _F =350/700mA	840	---	860	nm
Reverse Current (漏电流)	I _R	V _R =5V	---	---	10	uA

Vie.22 42.6 443.83 1

Table 1-2 Absolute Maximum Ratings at Ts=25°C 绝对最大值





2. Packaging 产品包装

2.1 Packaging Specification 包装规格

Package: 1000pcs/reel. 包装每卷

2.1.1 Carrier Tape Dimension 载带尺寸

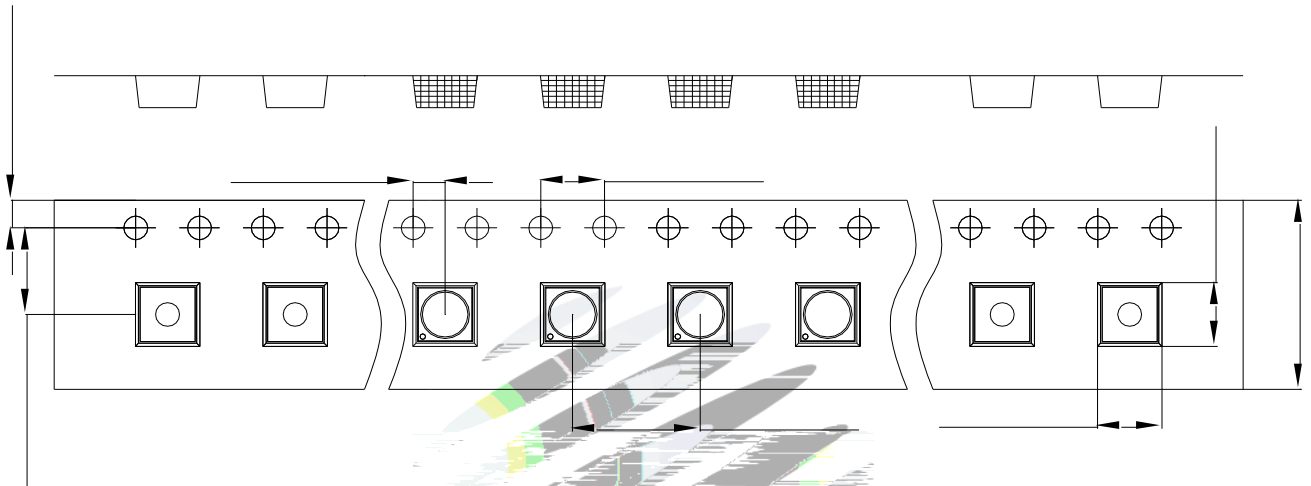


Fig.2-1 Carrier Tape Dimension 载带尺寸

2.1.2 Reel Dimension 卷盘尺寸

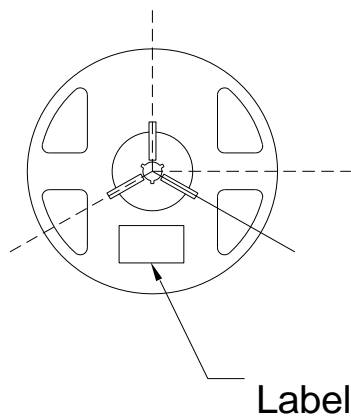


Fig.2-2 Reel 卷盘

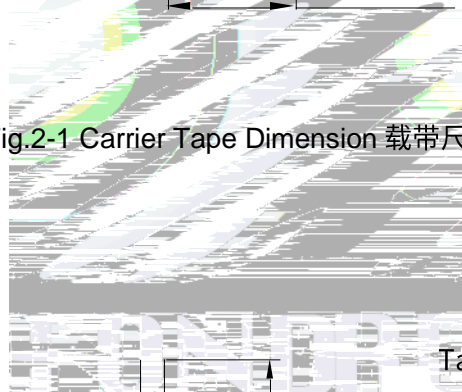


Table 2-1 Reel Dimension 卷盘尺寸

A	14.0±0.5mm
B	178±1mm
C	59±1mm
D	13.9±0.5mm

Notes 备注:

The tolerances unless mentioned ± 0.1 mm. Unit : mm 注: 未注公差为 ± 0.1 毫米, 尺寸单位: 毫米。

2.4 Reliability Test Items And Conditions 信赖性测试项目及条件

Table 2-3 Test items and conditions 测试项目及条件

Test Items 项目	Ref. Standard 参考标准	Test Condition 测试条件	Time 时间	Quantity 数量	Ac/Re 接收/拒收
Reflow 回流焊	JESD22-B106	T _{emp} : 260°C max T=10 sec	2 times.	10 pcs.	0/1
Thermal Shock 冷热冲击	JEITAED-4701 300307	-40°C 15min 10s 100°C 15min	500 cycles.	10 pcs.	0/1
High Temperature Storage 高温保存	JEITAED-4701200201	T _{emp} : 100°C	1000 hrs.	10 pcs.	0/1
Low Temperature Storage 低温保存	JEITA ED-4701200 202	T _{emp} : -40°C	1000 hrs.	10 pcs.	0/1
Life Test 常温通电	JESD22-A108	T _A =25°C I _F =350mA	1000 hrs.	10 pcs.	0/1
High Temperature High Humidity Life Test 高温高湿通电	JESD22-A101	60°C/ 90%RH I _F =350mA	1000 hrs.	10 pcs.	0/1

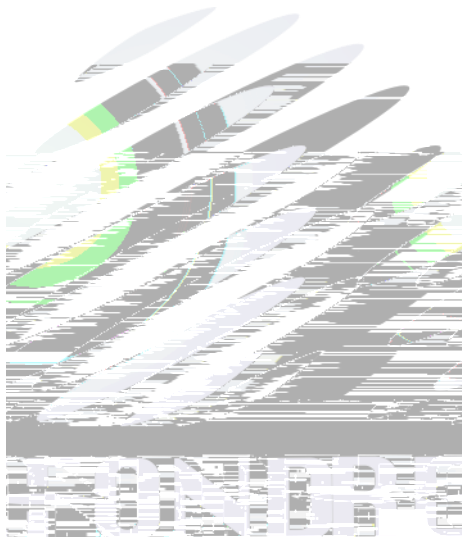
2.5 Criteria For Judging Damage 失效判定标准

Table 2-4 Criteria for judging damage 失效判定标准

Test Items 项目	Symbol 符号	Test Condition 测试条件	Criteria For Judgement 判定标准	Applicable project 适用项目
Forward Voltage 电压	V_F	$I_F=350\text{mA}$	$\leq \pm 10\%$	Reflow Thermal Shock
Total radiant flux 辐射功率		$I_F=350\text{mA}$	Maintenance $\geq 80\%$ 辐射功率维持率	High and Low Temperature Storage Life Test
Lamp Bead Light Test 灯珠点亮测试	/	$I_F=350\text{mA}$	No open circuit short circuit or flicker 无开路、短路、闪变	High Temperature High Humidity Life Test

Notes 备注:

- The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform, the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others. 以上可靠性测试是基于瑞丰现有实验平台单颗/条 LED 在良好散热条件验证下的结果。客户端将 LED 应用于串、并联线路时热等问题，需自行评估电流、电压分配。敬
- The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license. 以上技术数据仅为产品的典型值，只作为参考，不作为任何应用条件及应用方式的保证。



Hold time within 5 °C with the actual peak temperature (TP) 与实际峰值温度 (TP) 相差 5 °C 以内的保持时间	Max 30s 最多30秒
Cooling speed 降温速度	Max 6 °C/ s 最高6 °C/秒
Needed time from 25 °C to Tp 25 °C 升至峰值温度所需时间	Max 8 minutes 最多8分钟

Notes 备注:

- (1) The number of reflows should not exceed two, and if the time between reflows exceeds 24 hours, the LED may be damaged due to moisture absorption. 回流焊次数不可以超过两次，两次回流焊的时间间隔如果超过24小时，LED可能由于吸湿而损坏。
- (2) When welding, do not press hard on the surface of the gel while the material is hot. 当焊接时，不要在材料受热时用力压胶体表面。

3.1.1 Soldering Iron 烙铁焊接

- (1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds 当手工焊接时,烙铁的温度必须小于300°C，时间不可超过3秒。
- (2) Soldering by hand should be done only one time. 手工焊接只可焊接一次。

3.1.2 Repairing 修补

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED 一旦焊接后,再高温烙铁修补,会对LED本身特性造成破坏,因此,在焊接LED时,应使用双头烙铁,且应事先确认LED的特性是否会损坏LED本身的特性。

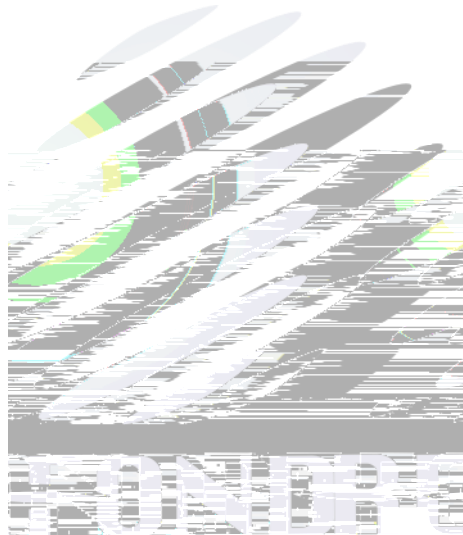
3.1.3 Cautions 注意事项

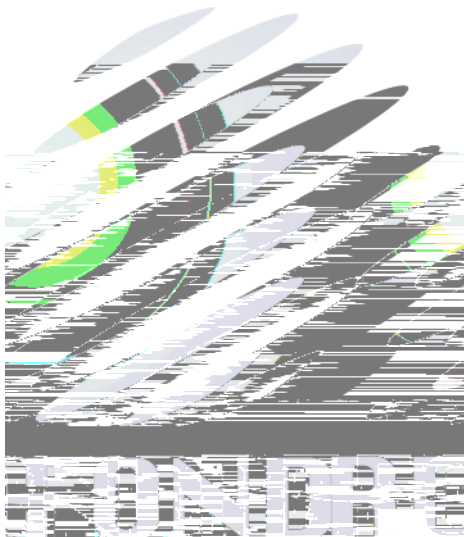
- (1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use

the picking up nozzle, the pressure on the silicone resin should be proper. LED封装胶为硅胶，表面较软，受外力挤压时容易变形，从而影响LED可靠性，因此应有预防措施避免在按压器件，当使用吸嘴时，胶体表面的压力应是恰当的。

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board. LED灯珠不要焊接在弯曲的PCB板上，焊接完成后不要弯曲PCB板。

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.回流焊之后冷却过程中，不要对材料施加外力，也不要震动，回流焊后，不要采用激剧冷却的方式。





(4) Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry. 通过使用适当的工具从材料侧面夹取，不可直接用手或尖锐金属压胶体表面，它可能会损坏内部电路。

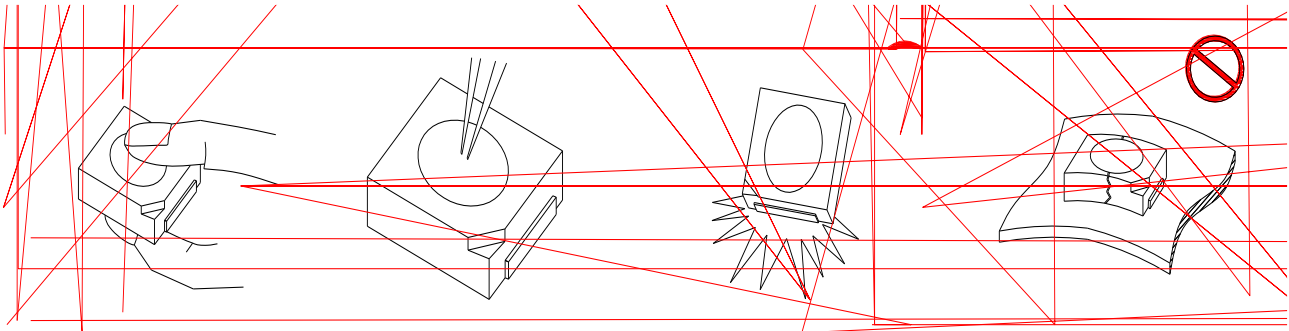


Fig 4-1 Misoperation 错误操作

(5) In designing a circuit, the current through each LED must be exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage. 设计电路时，通过 LED 的电流不能超过规定的最大值，同时，还需使用保护电阻，否则，微小的电压变化将会引起电流的较大变化，可能烧毁 LED。电路设计必须保证只有在开启或者关闭的时候出现正向电压的变化，不要施加反压，否则会损坏 LED。

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED 容易因为自身的发热和环境的温度改变而改变，温度升高会降低 LED 发光效率，影响发光颜色，所以在设计时应充分考虑散热问题。

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause

damage to the LED. 与其他封装胶相比，硅胶通常较软，表面易吸附脏物，应用时应特别注意，当清洗方式，我们推荐异丙醇作清洗剂，如对产品洁净度要求较高时，回流焊以后需要采用恰当的需要用到其他清洗剂，必须保证不会破坏封装体，超声清洗可能会对 LED 带来损害，不推荐这种清洗方式。

Table 4-1 Storage 储存

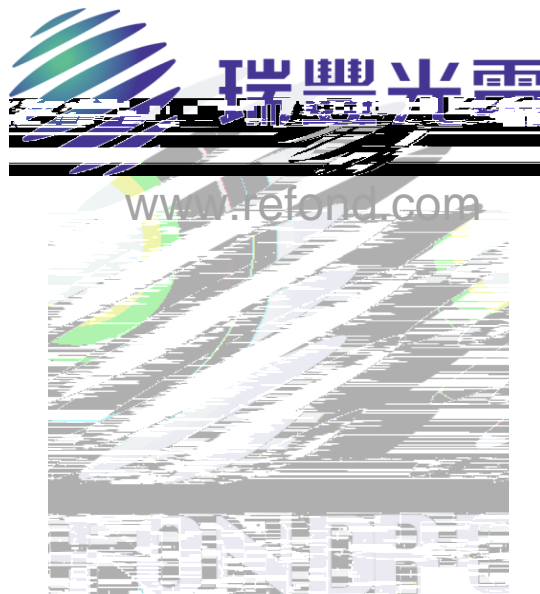
Conditions 种类		Temperature	Humidity 湿度	Time 时间
Storage	Before Opening Aluminum Bag 拆包前	30°C	75%	Within 6 Months From Date 6个月内
	After Opening Aluminum Bag 拆包后	30°C	60%	168hours 168小时
Baking 烘烤		60±5°C	<5%	≥24hours 大于24小时

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition 60±5 and less than 5%RH for above 24 hours. 如果硅胶失效或产品已经超过或者产品不符合以上有效储存条件，需拆包后进行烘烤，烘烤条件：60±5°C，小于 5%RH，大于 24 小时。

If the package is flatulence or damaged, please notify the sales staff to assist. 如果包装胀气或者

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). 和其他的半导体元器件一样，LED 对静电过流击穿非常敏感，需要做好防护。

(10) Other points for attention, please refer to our relevant information. 其它注意事项请参照瑞丰相关资料。



Declare 申明

This specification is written both in English and in Chinese and the latter is formal.

产品规格书以中英文方式书写，~~如有冲突以中文版为准~~